

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSV)

2SK2679

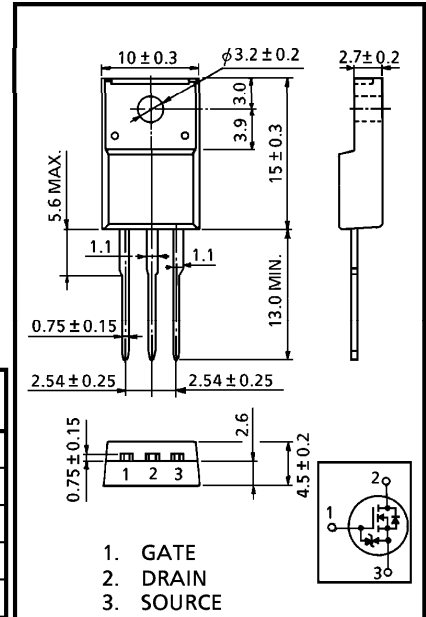
HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS

Unit in mm

- Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.84 \Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 4.4 S$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100 \mu A$ (Max.) ($V_{DS} = 400 V$)
- Enhancement-Mode : $V_{th} = 2.0 \sim 4.0 V$
($V_{DS} = 10 V, I_D = 1 mA$)



MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	400	V
Drain-Gate Voltage ($R_{GS} = 20 k\Omega$)		V_{DGR}	400	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	DC	I_D	5.5	A
	Pulse	I_{DP}	22	A
Drain Power Dissipation ($T_c = 25^\circ C$)		P_D	35	W
Single Pulse Avalanche Energy**		E_{AS}	223	mJ
Avalanche Current		I_{AR}	5.5	A
Repetitive Avalanche Energy*		E_{AR}	3.5	mJ
Channel Temperature		T_{ch}	150	$^\circ C$
Storage Temperature Range		T_{stg}	$-55 \sim 150$	$^\circ C$

JEDEC	—
EIAJ	SC-67
TOSHIBA	2-10R1B

Weight : 1.9 g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	3.57	$^\circ C/W$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	62.5	$^\circ C/W$

Note ;

* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

** $V_{DD} = 90 V, T_{ch} = 25^\circ C$ (initial), $L = 12 mH, R_G = 25 \Omega, I_{AR} = 5.5 A$

This transistor is an electrostatic sensitive device.

Please handle with caution.

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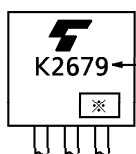
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Gate Leakage Current	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	—	—	±10	μA	
Gate-Source Breakdown Voltage	V _{(BR)GSS}	I _G = ±10 μA, V _{DS} = 0 V	±30	—	—	V	
Drain Cut-off Current	I _{DSS}	V _{DS} = 400 V, V _{GS} = 0 V	—	—	100	μA	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	400	—	—	V	
Gate Threshold Voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V	
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 3 A	—	0.84	1.2	Ω	
Forward Transfer Admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	4.4	—	S	
Input Capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	720	—	pF	
Reverse Transfer Capacitance	C _{rss}		—	80	—		
Output Capacitance	C _{oss}		—	250	—		
Switching Time	Rise Time	t _r		—	15	—	ns
	Turn-on Time	t _{on}		—	30	—	
	Fall Time	t _f		—	25	—	
	Turn-off Time	t _{off}		V _{IN} : t _r , t _f < 5 ns Duty ≤ 1%, t _w = 10 μs	—	110	
Total Gate Charge (Gate-Source Plus Gate-Drain)	Q _g	V _{DD} ≐ 320 V, V _{GS} = 10 V, I _D = 5.5 A	—	17	—	nC	
Gate-Source Charge	Q _{gs}		—	10	—		
Gate-Drain ("Miller") Charge	Q _{gd}		—	7	—		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I _{DR}	—	—	—	5.5	A
Pulse Drain Reverse Current	I _{DRP}	—	—	—	22	A
Diode Forward Voltage	V _{DSF}	I _{DR} = 5.5 A, V _{GS} = 0 V	—	—	-1.7	V
Reverse Recovery Time	t _{rr}	I _{DR} = 5.5 A, V _{GS} = 0 V dI _{DR} /dt = 100 A/μs	—	350	—	ns
Reverse Recovery Charge	Q _{rr}		—	2.1	—	μC

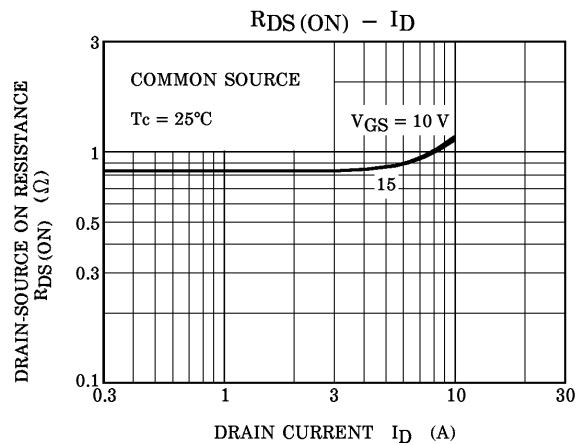
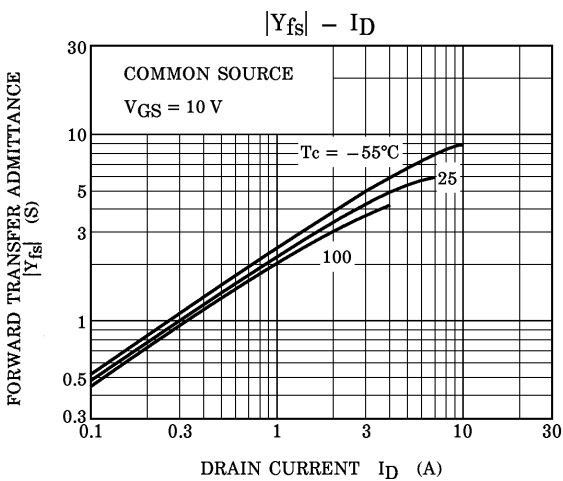
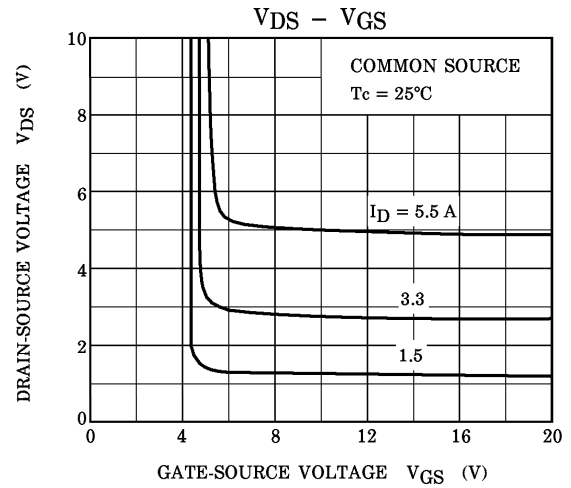
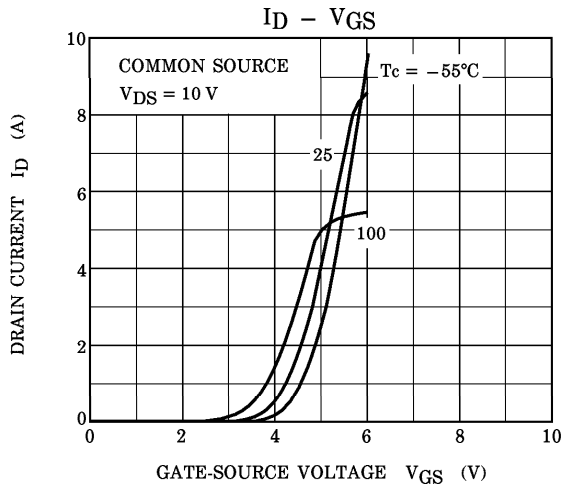
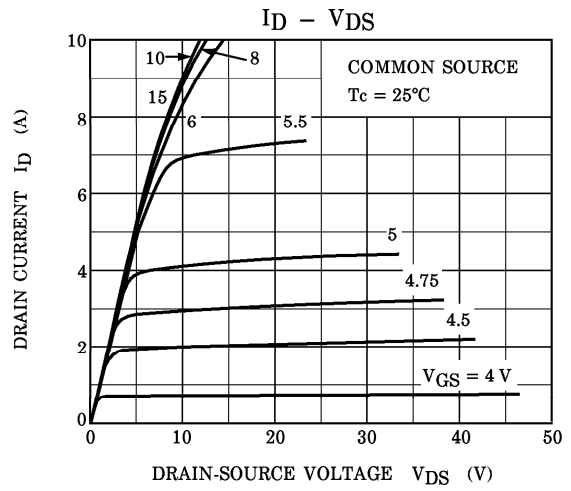
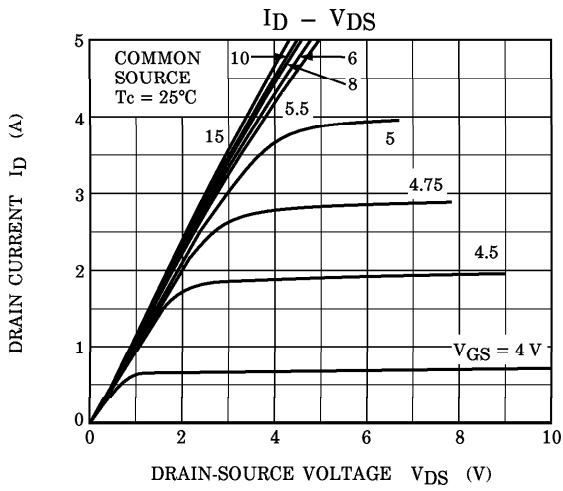
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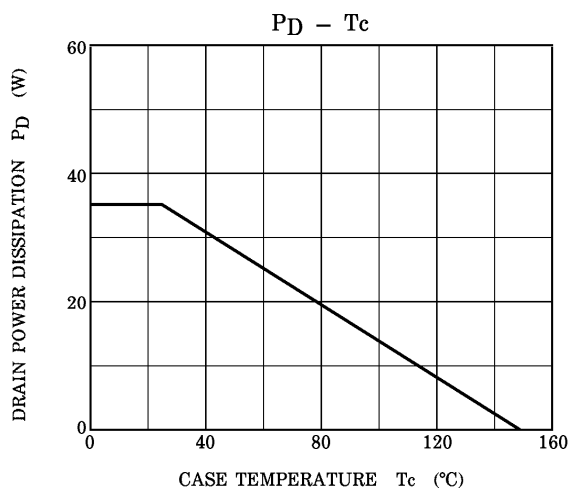
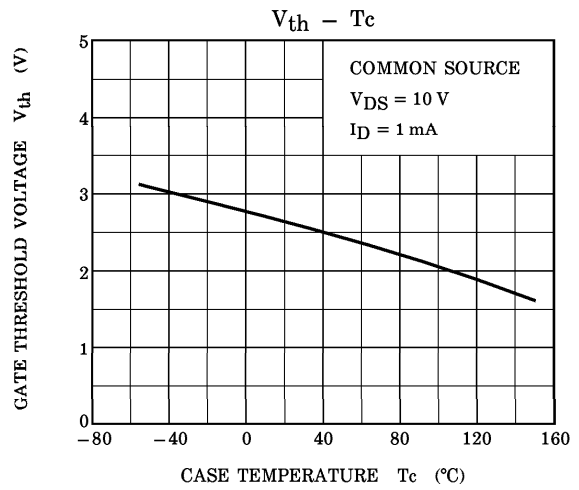
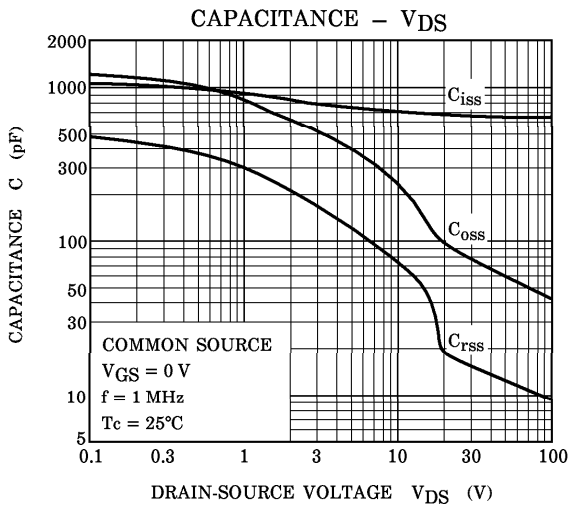
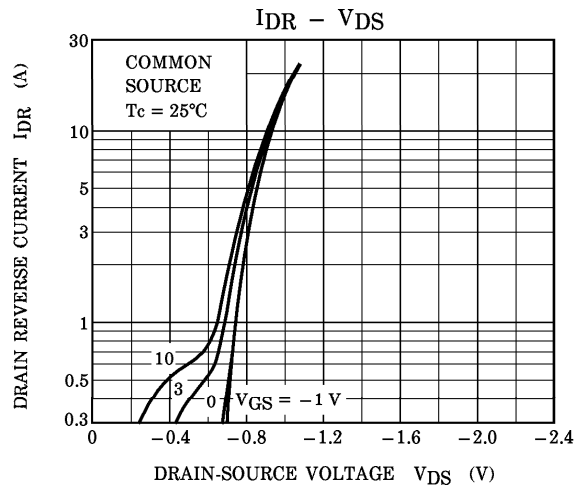
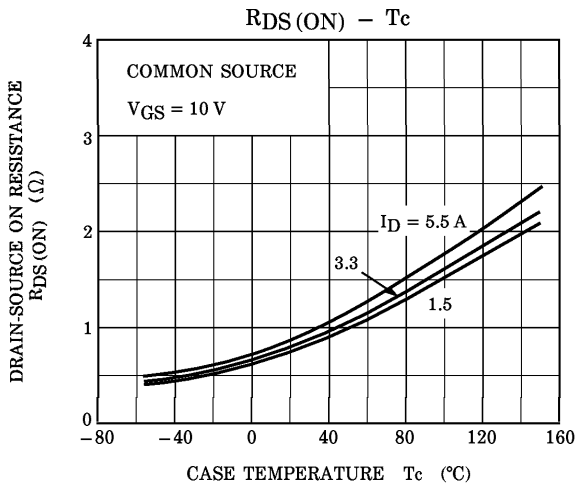


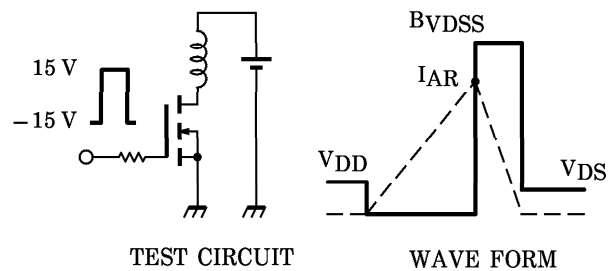
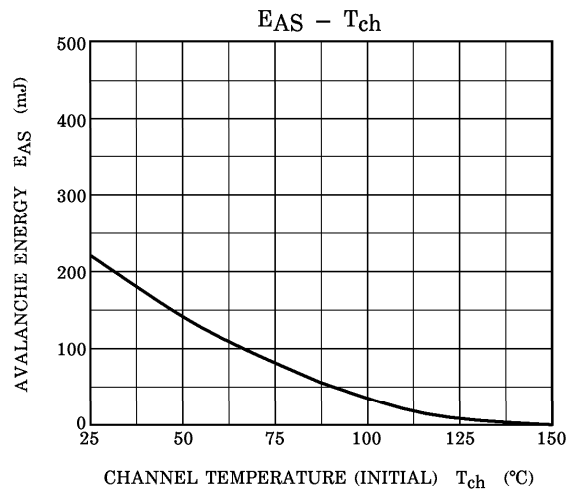
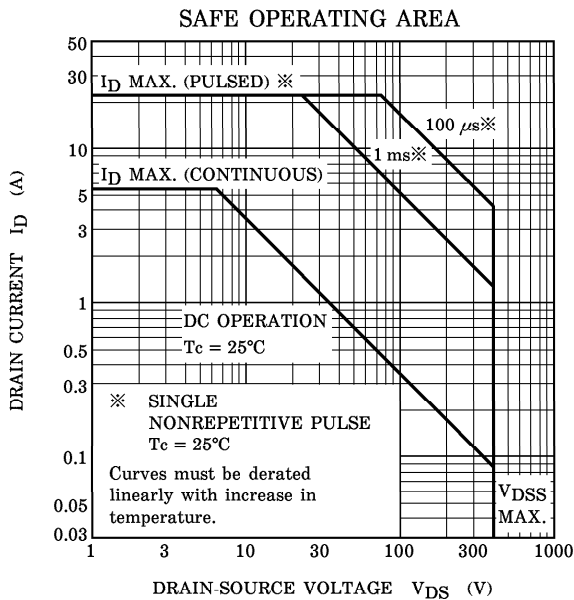
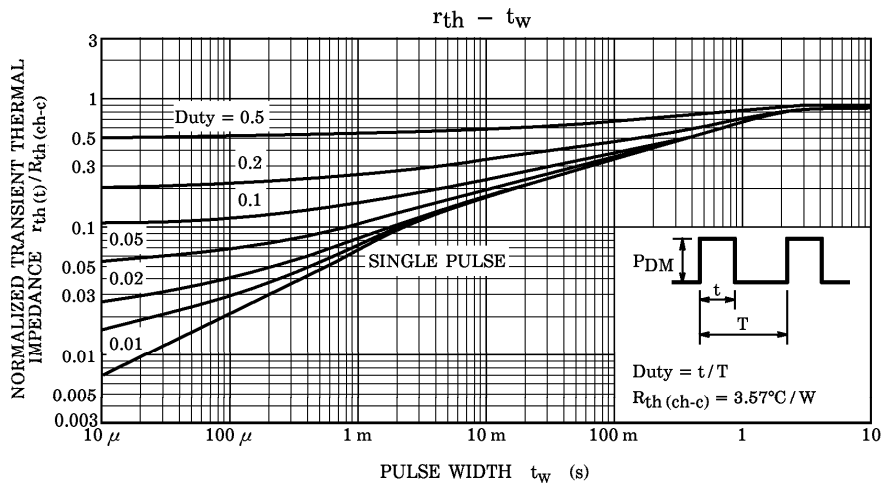
※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)







Peak $I_{AR} = 5.5 A$, $R_G = 25 \Omega$

$V_{DD} = 90 V$, $L = 12 mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$